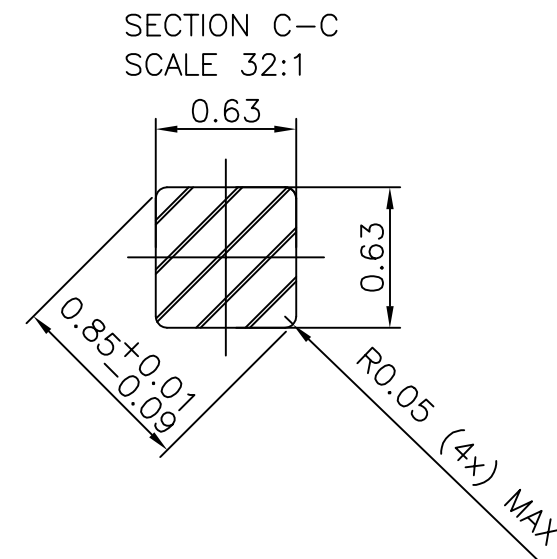
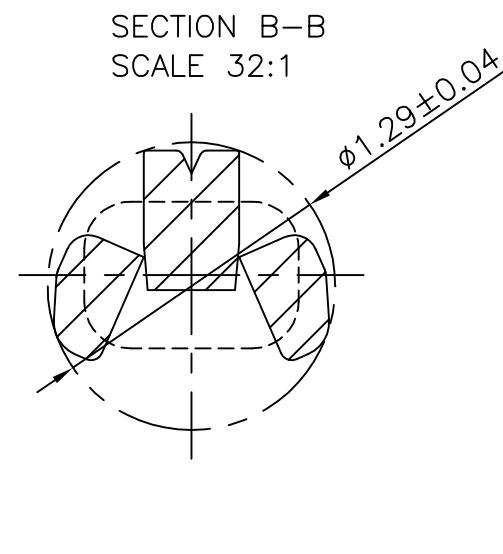
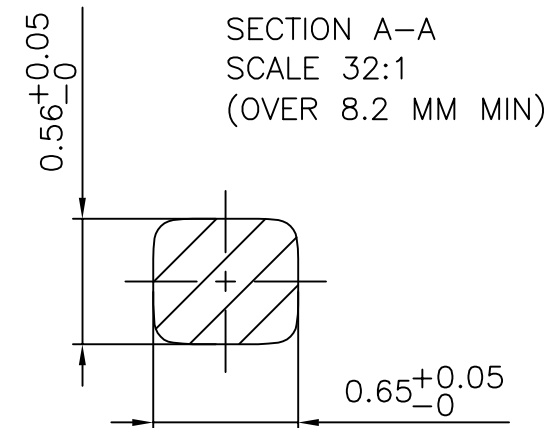
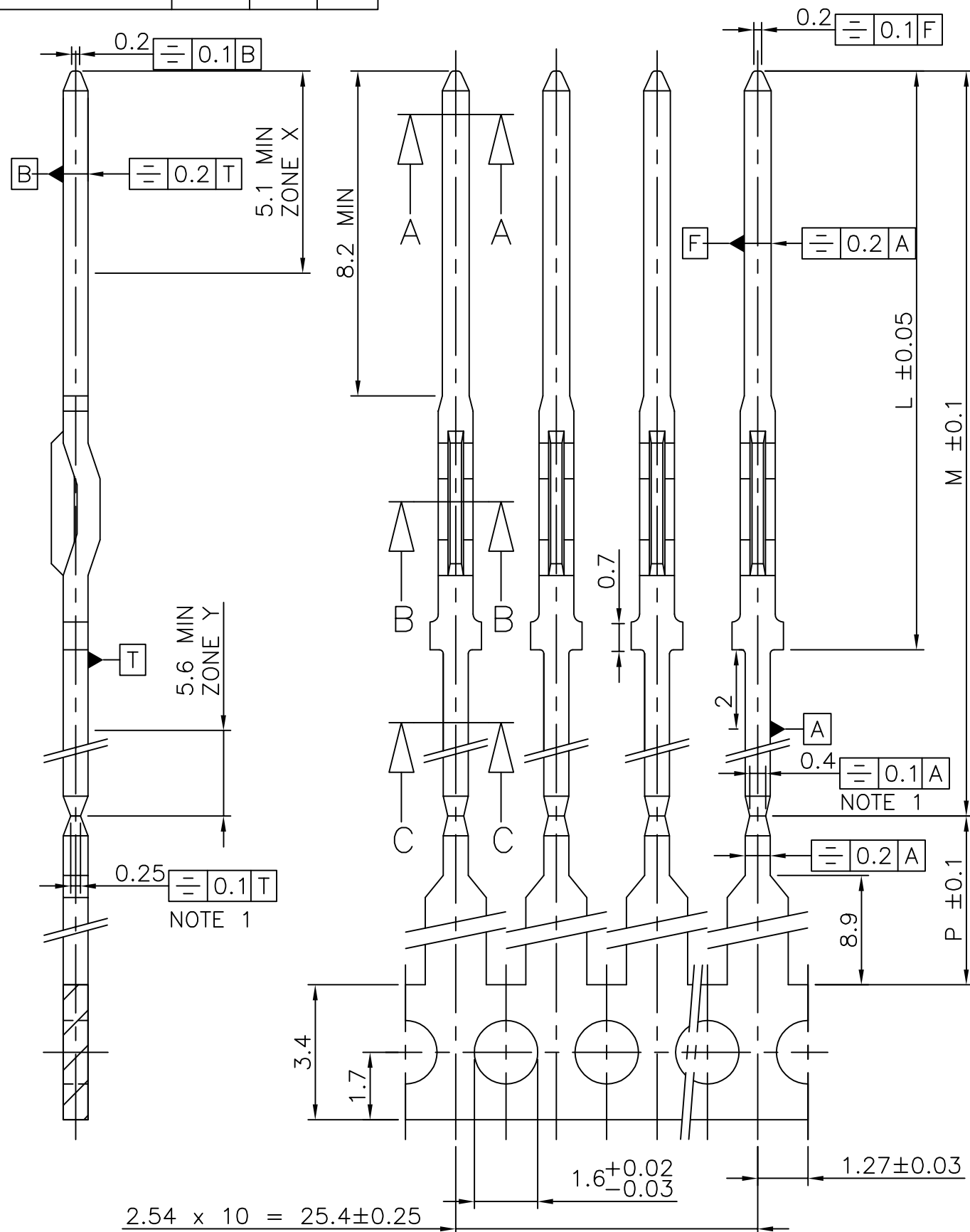


PRODUCT NUMBER	L	M	P
PINB164MC3--	14.55	16.4	17.5
PINB170MC3--	15.15	17.0	17.5
PINB234MC3--	14.55	23.5	10.4

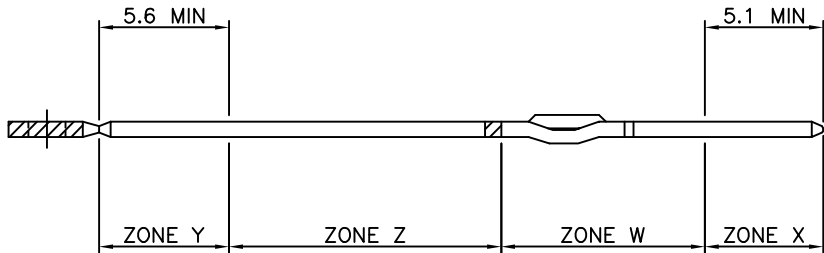


- NOTES:
- 1 - ECCENTRICITIES ARE VALID AFTER REMOVAL OF CARRYING STRIP.
 - 2 - PLATING: SEE SHEET 2.
 - 3 - CONTACT MATERIAL: COPPER ALLOY

EUROPEAN PROJECTION

mat'l. code SEE NOTES				surface ISO 1302	tolerance ISO 406 ISO 1101	projection mm	product family PIN-B			
ltr	ecn no	dr	date	tolerances unless otherwise specified		mm	title PRESS-FIT PIN COMPLIANT VXX27635			
A	F03021	DLE	2003-03-03	angles	linear					
B	I05-0243	MINI	2005-11-22				dwg no VJW 55144			
C	I06-0113	MINI	2006-07-11	$\pm 1^\circ$		scale 8:1				
D	I07-0130	KR	2007-10-04	dr	D.LEGRAND	2003-03-03	sheet 1 of 2 size A3			
				enr	F.TISSERAND	2003-03-03				
				chr	KESAVAN.R	2007-10-04	type Product Customer Drawing			
				appd	RAKHEE GEORGE	2007-10-04				
sheet index	revision sheet	D	D							
		1	2							

CONTACT TYPE	PLATING CODE	PLATING				CLASS	PRODUCT NO. CUSTOMER CODE
		ZONE Y	ZONE Z	ZONE W	ZONE X		
PINB (DRY PRESS-FIT)	GY	0.8μ Au MIN. OVER 2μ Ni MIN. OR (0.065μ Au MIN. + 0.69μ PdNi MIN.) OVER 2μ Ni MIN.	2 μ Ni MIN	0.05-1 μ SnPb OVER 2 μ Ni MIN	0.8μ Au MIN. OVER 2μ Ni MIN. OR (0.065μ Au MIN. + 0.69μ PdNi MIN.) OVER 2μ Ni MIN.	GRADE 1	1AB001520017 (PINB234MC3GY)
	GR	2 μ Ni MIN	2 μ Ni MIN	0.05-1 μ SnPb OVER 2 μ Ni MIN	0.8μ Au MIN. OVER 2μ Ni MIN. OR (0.065μ Au MIN. + 0.69μ PdNi MIN.) OVER 2μ Ni MIN.	GRADE 1	
	GW	0.8μ Au MIN. OVER 2μ Ni MIN. OR (0.065μ Au MIN. + 0.69μ PdNi MIN.) OVER 2μ Ni MIN.	2 μ Ni MIN	0.05-1 μ SnPb OVER 2 μ Ni MIN	2 μ Ni MIN	GRADE 1	
	GC	0.4μ Au MIN. OVER 2μ Ni MIN. OR (0.065μ Au MIN. + 0.38μ PdNi MIN.) OVER 2μ Ni MIN.	2 μ Ni MIN	0.05-1 μ SnPb OVER 2 μ Ni MIN	0.4μ Au MIN. OVER 2μ Ni MIN. OR (0.065μ Au MIN. + 0.38μ PdNi MIN.) OVER 2μ Ni MIN.	GRADE 1	
	Z1	0.05-1 μ SnPb OVER 2 μ Ni MIN	0.05-1 μ SnPb OVER 2 μ Ni MIN	0.05-1 μ SnPb OVER 2 μ Ni MIN	0.4μ Au MIN. OVER 2μ Ni MIN. OR (0.065μ Au MIN. + 0.38μ PdNi MIN.) OVER 2μ Ni MIN.	GRADE 1	PINB164MC3Z1



- NOTES :
- 1. GOLD THICKNESS MEASURED WITH FISHERSCOPE X-RAY.
MEASUREMENT OF GOLD THICKNESS WITHOUT CORRECTION FACTOR
FOR THE GOLD DENSITY (DENSITY = 19.3)
 - 2. THE "LF" PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY
REGULATIONS AS DESCRIBED IN GS-22-008.
 - 3. "LF" SUFFIX TO PRODUCT NUMBER FOR LEAD FREE/ROHS COMPATIBLE VERSION.
 - 4. FOR "LF" PRODUCTS SnPb PLATING IS REPLACED BY MATTE TIN.
NO CHANGE IN PLATING THICKNESS AND UNDERCOAT PLATING.
 - 5. FOR "LF" PRODUCTS LEAD FREE OR ROHS DIRECTIVE LABELLING
TO BE PROVIDED AS PER PACKAGING SPECIFICATION GS-14-920.

mat'l. code				surface		tolerance		projection		product family									
-				ISO 1302		ISO 406 ISO 1101				PIN-B									
ltr	ecn no	dr	date	tolerances unless		otherwise specified				title									
A	F03021	DLE	2003-03-03	angles	linear	0.1±0.2													
B	I05-0243	MINI	2005-11-22			0.01±0.1													
C	I06-0113	MINI	2006-07-11			±1°													
D	I07-0130	KR	2007-10-04	dr	D.LEGRAND		2003-03-03				dwg no		sheet 2 of 2		size				
				engr	F.TISSERAND		2003-03-03				VJW		55144		A3				
				chr	KESAVAN.R		2007-10-04				type Product Customer Drawing								
				appd	RAKHEE GEORGE		2007-10-04												
sheet index		revision sheet																	

Mouser Electronics

Authorized Distributor

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